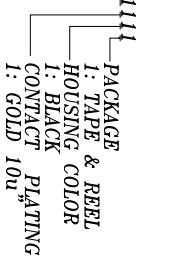
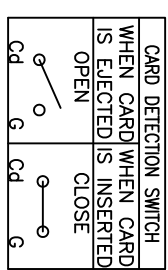
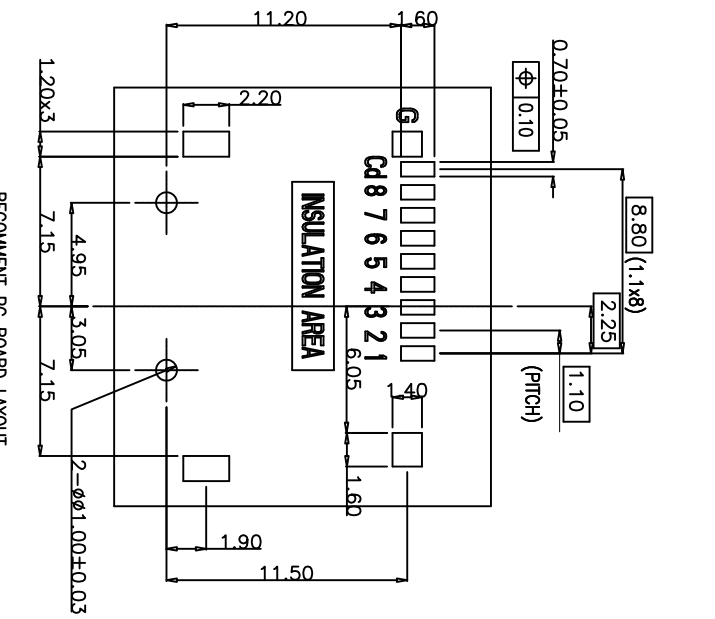
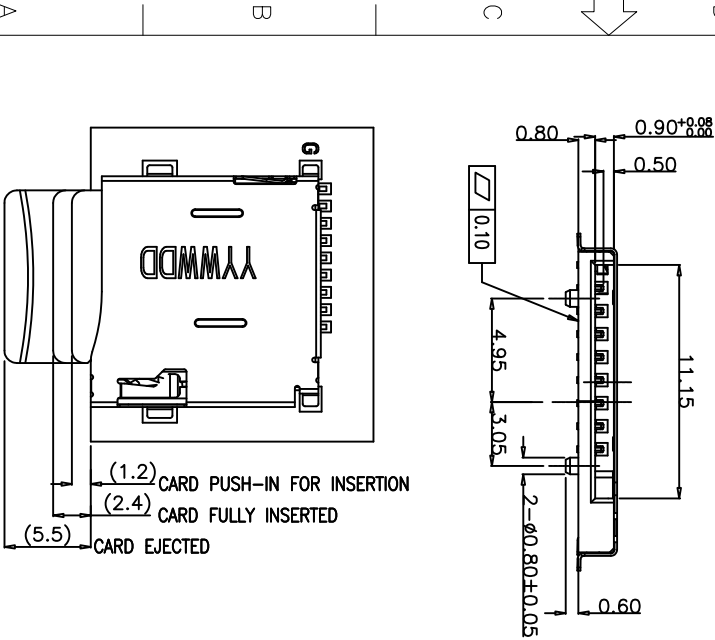
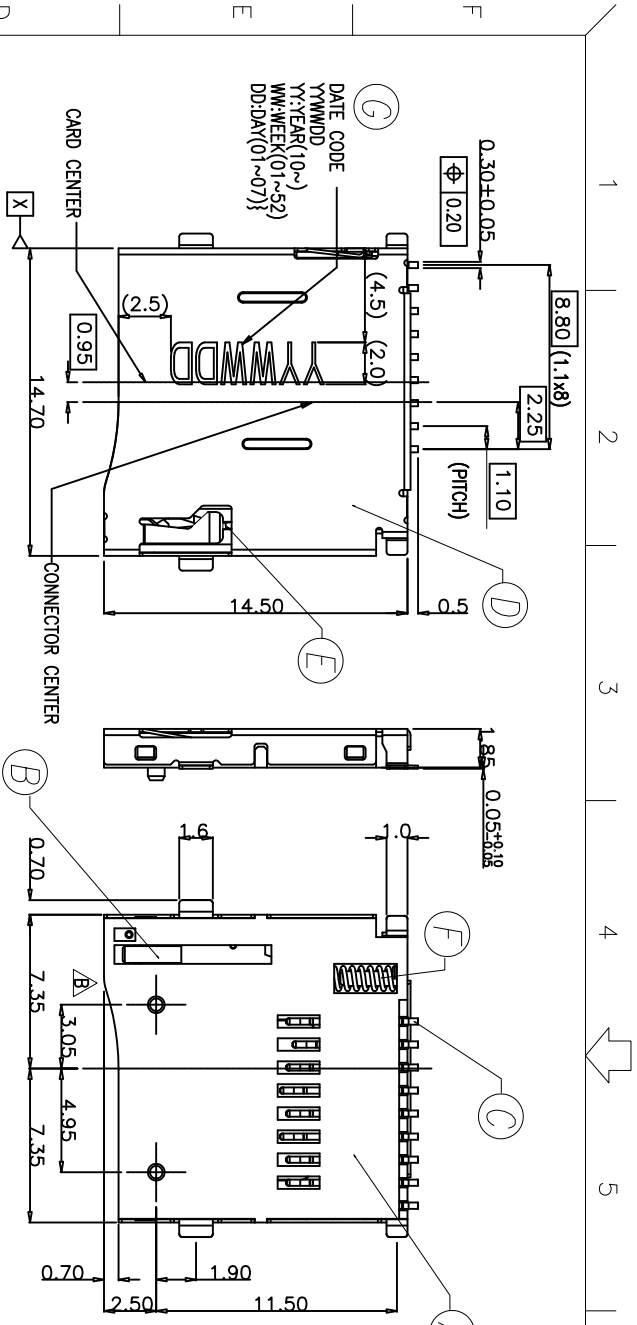


REV.	ECN NO.	OR DESCRIPTION	REVISED	DATE
A	ECR NO:L100015	NY-C		2010.05.03
B	2SD1503-000X111 → 2SD1503-001111	NY-C		2010.05.03
	ECN NO:L100116	NY-C		2010.12.01

- SPECIFICATIONS:
1. SEE "2SD1503 SERIES" SPECIFICATIONS.
  2. TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
  3. FOR REFLOW SOLDERING LEAD-FREE PROCESS.
  4. HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING.
  5. PACKAGE : SEE "2SD1503 SERIES" PACKAGE.



PIN NUMBER	PIN ASSIGNMENT	PIN NUMBER	PIN ASSIGNMENT
1	DATA2	6	VSS
2	CD/DAT3	7	DATA0
3	CMD	8	DATA1
4	VDD	Cd	CARD DETECTION
5	CLK	G	GROUND



NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
G	INK	1		BLACK
F	SPRING	1	PIANO WIRE	
E	DRAG LINK	1	SUS304	
D	SHELL	1	SUS304R-3/4H	IN PLATING; SOLDER AREA: GOLD FLASH
C	CONTACT	9	C5210R-EH	GOLD 10u"
B	SLIDER	1	LCP UL 94V-0	BLACK COLOR
A	BODY	1	LCP UL 94V-0	BLACK COLOR
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS: ANGLES:

X : ±0.5 X : ±2°  
X.X : ±0.3 X.X : ±1°  
X.XX : ±0.2

Singatron Enterprise Co., Ltd.  
信音企業股份有限公司

T FLASH/MICRO SD CARD PUSH TYPE CONN.

DWN IN-C-2010.12.01 PART NO. 2SD1503-001111  
CHKD DMM-1-2010.12.01 SCALE 1:1 UNIT: mm  
APVD DMM-1-2010.12.01 SIZE: A3 SHEET: 1 OF 1 REV: B

CUSTOMER COPY